

# **International Exhibition & Conference for Power Electronics, Intelligent Motion, Renewable Energy and Energy Management (PCIM Europe 2018)**

Power for Efficiency

Nuremberg, Germany  
5 - 7 June 2018

Volume 1 of 3

ISBN: 978-1-5108-6498-6

**Printed from e-media with permission by:**

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57 Morehouse Lane  
Red Hook, NY 12571



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**pcim Europe**  
Best Paper Award  
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**Highly Integrated Two-Phase SiC Boost Converter with 3D Printed Fluid Coolers and 3D Printed Inductor Bobbins .....317**  
Arne Hendrik Wienhausen, Alexander Sewergin, Rik W. de Doncker, RWTH Aachen University, D



**pcim Europe**  
Young Engineer Award  
**WINNER**

**Young Engineer Award – Winner**

**25 kW High Power Resonant Inverter Operating at 2.5 MHz based on SiC SMD Phase-Leg Modules .....714**  
Fabian Denk, Karsten Haehre, Christoph Simon, Santiago Eizaguirre, Michael Heidinger, Rainer Kling, Wolfgang Heering, Karlsruhe Institute of Technology (KIT), D

**Reducing the dv/dt of Motor Inverters by a Two Leg Resonant Switching Cell .....1636**  
Thomas Fuchslueger, Hans Ertl, Technical University of Vienna, AT; Markus Vogelsberger, Bombardier Transportation, AT

**High Efficiency Three-Level Simplified Neutral Point Clamped (3L-SNPC) Inverter with GaN-Si Hybrid Structure .....1726**  
Alexander Lange, Jennifer Lautner, Bernhard Piepenbreier, Friedrich Alexander University Erlangen, D

## Table of Content PCIM Europe 2018

### Special Session: Advanced Solutions for Charging of Electric Vehicles

<b>1</b>	<b>85 kHz Band Wireless Charging System for EV or Electric Bus</b> .....	<b>31</b>
	Akihisa Matsushita, Fumiaki Takeuchi, Shuichi Obayashi, Masaaki Ishida, Toshiba, J; Tatsuro Abe, Toshiba Infrastructure Systems & Solutions Corporation, J	
<b>2</b>	<b>Advanced Vehicle Charging Solutions Using SiC and GaN Power Devices</b> .....	<b>38</b>
	Bernd Eckardt, Moritz Wild, Christopher Joffe, Stefan Zeltner, Stefan Endres, Fraunhofer Institute IISB, D; Martin März, FAU Erlangen-Nuremberg, D	
<b>3</b>	<b>System Architectures for Multiports, Bidirectional and Buffered Charging Unit for EV's</b> .....	<b>44</b>
	Alfred Rufer, EPFL, CH	

### Special Session: Materials for Packaging and Thermal Management

<b>4</b>	<b>Development of High Temperature Silicone Gels</b> .....	<b>49</b>
	Makoto Ohara, Shin-Etsu Silicones Europe, D	
<b>5</b>	<b>Silicone Gels for Continuous Operation up to 200 C in Power Modules</b> .....	<b>51</b>
	Thomas Seldrum, Francois Vanderhaeghen, The Dow Chemical Company, BE; Hiroji Enami, The Dow Chemical Company, J	
<b>6</b>	<b>High Temperature Encapsulation for Smart Power Devices</b> .....	<b>57</b>
	Karl-Friedrich Becker, Mattis Obst, Jörg Bauer, Tanja Braun, Fraunhofer-Institute IZM, D; T. Thomas, M. Schneider-Ramelow, Klaus-Dieter Lang, Technical University Berlin, D	
<b>7</b>	<b>Next-Generation PPS Grades for Power Module Applications</b> .....	<b>62</b>
	Christian Schirmer, Yuki Ota, Toray Resins Europe, D	

### SiC based Power Module

<b>8</b>	<b>New SiC 1200 V Power MOSFET &amp; Compact 3.25 mOhm, 41 mm Power Module for Industrial Applications</b> .....	<b>66</b>
	Jeffrey Casady, Shadi Sabri, Sei-Hyung Ryu, Ty McNutt, Brett Hull, Brice McPherson, Sayan Seal, Jennifer Stabach, Austin Curbow, Dan Martin, Zach Cole, Brandon Passmore, Alex Lostetter, Scott Allen, John Palmour, Wolfspeed – A Cree Company, USA	
<b>9</b>	<b>A Wire-bond-less 10 kV SiC MOSFET Power Module with Reduced Common-mode Noise and Electric Field</b> .....	<b>74</b>
	Christina DiMarino, Dushan Boroyevich, Rolando Burgos, Yue Xu, Center for Power Electronics Systems Virginia Tech, USA; Ke Li, Bassem Mouawad, Mark Johnson, University of Nottingham, UK	
<b>10</b>	<b>Enhanced Breakdown Voltage and High Current of All-SiC Modules with 1st Generation Trench Gate SiC MOSFETs</b> .....	<b>81</b>
	Motohito Hori, Yuichiro Hinata, Katsumi Taniguchi, Masayoshi Nakazawa, Yoshinari Ikeda, Tomoyuki Yamazaki, Fuji Electric, J; Thomas Heinzl, Fuji Electric Europe, D	
<b>11</b>	<b>Highly Integrated SiC-power Modules for Ultra-Fast Lithium Ion Battery Chargers in LLC-Topology</b> .....	<b>87</b>
	Thomas Blank, Bao Ngoc An, Dominik Bauer, Patrick Jochem, Matthias Luh, Helge Wurst, Marc Weber, Karlsruhe Institute of Technology, D	

## Traction Inverters

- 12 Effects of a SiC TMOSEFET Traction Inverters on the Electric Vehicle Drivetrain .....95**  
Alexander Nisch, Christian Klöffer, Jörg Weigold, Wolfgang Wondrak, Daimler, D; Christian Schweikert, Laurent Bearenaud, Infineon, D
- 13 Highly Integrated Traction Inverter for a Modular Drive Concept .....103**  
Ulf Schümann, Jasper Schnack, Ronald Eisele, Dominik Hilper, University of Applied Sciences Kiel, D; Christian Mertens, Patrick Heumann, Volkswagen, D; Hans-Jürgen Schliwinski, Malte Päsler, Jörn Hinz, Fraunhofer Institute ISIT, D; Mathias Kamprath, Annika Zastrow, Vishay Siliconix, D; Holger Beer, Frank Osterwald, Danfoss Silicon Power, D; Thomas Ebel, Sven Brückner, Hannes Wolff, FTCAP, D; Hagen Reese, Sergej Schikowski, Reese und Thies, D
- 14 Automotive Traction Inverter Utilizing SiC Power Module .....111**  
Masaharu Nakanishi, Kenji Hayashi, Akifumi Enomoto, Masashi Hayashiguchi, Motohiro Ando, Kazuhide Ino, ROHM, Ltd, J; Aly Mashaly, Christian Felgemacher, Guenter Richard, ROHM Semiconductor, D
- 15 Novel Approach of Integrated Motor-Inverter Power Module for 48 V Mild Hybrid Starter and Generator (MHSG) .....117**  
Jihwan Seong, Sangwon Yoon, Minki Kim, Jangmook Lim, Hobeom Han, Hanyang University, ROK; Semin Park, Hyunkyu Choi, Yuchoel Park, Pilkyoung Oh, Sang Min Kim, Taesuk Kwon, Hyundai Mobis, ROK

## Intelligent Motion

- 16 Decentralized Control of a Twelve-Phase PMSM .....125**  
Oliver Dieterle, Thomas Greiner, University of Applied Sciences Pforzheim, D
- 17 Computationally Efficient Predictive Direct Torque Control Strategy for PMSGs without Weighting Factors .....133**  
Mohamed Abdelrahem, Hisham Eldeeb, Christoph Hackl, Ralph Kennel, Technical University of Munich, D; Jose Rodriguez, University Andres Bello, CL
- 18 Switching Frequency Control for a DS-PWM .....141**  
Axel Klein, Malte Thielmann, Walter Schumacher, Technical University of Braunschweig, D
- 19 Improvements on a Sensorless Controlled Synchronous Reluctance Machine Down to Standstill .....149**  
Mario Nikowitz, Matthias Hofer, Manfred Schrödl, Technical University of Vienna, AT

## SiC Devices I

- 20 A 3.3 kV / 800 A Ultra-High Power Density SiC Power Module .....156**  
Takashi Ishigaki, Seiichi Hayakawa, Tatsunori Murata, Toshihito Tabata, Katsuyuki Asaka, Koyo Kinoshita, Tetsuo Oda, Kan Yasui, Toshiaki Morita, Daisuke Kawase, Yuji Takayanagi, Renichi Yamada, Katsuaki Saito, Hitachi Power Semiconductor Device, J; Toru Masuda, Hiroshi Miki, Masakazu Sagawa, Hidekatsu Onose, Kumiko Konishi, Ryusei Fujita, Hiroyuki Matsushima, Shintaroh Sato, Akio Shima, Hitachi, J
- 21 Efficiency Investigation of Full-SiC versus Si-based Automotive Inverter Power Modules at Equal Commutation Speed .....161**  
Ajay Poonjal Pai, Tomas Reiter, Infineon Technologies, D; Martin März, Fraunhofer Institute IISB, D



- 22 Applying the 2D-Short Circuit Detection Method to SiC MOSFETs Including an Advanced Soft Turn Off .....169**  
Patrick Hofstetter, Stefan Hain, Mark-M. Bakran, University of Bayreuth, D

### Advanced Packaging Technologies I

- 23 Investigation of Ton Dependency of Al-Clad Cu Bond Wires Under Power Cycling Tests .....176**  
Nan Jiang, Josef Lutz, Chemnitz University of Technology, D; Benjamin Fabian, Marko Kalajica, Heraeus, D
- 24 System Cost Reduction with Integration of Shunts in Power Modules in the Power Range Above 75 kW .....182**  
Klaus Vogel, Michael Gadermann, Andreas Schmal, Christoph Urban, Infineon Technologies, D
- 25 Cost Effective Direct-Substrate Jet Impingement Cooling Concept for Power Application .....189**  
Bassem Mouawad, Robert Abebe, Robert Skuriat, Jianfeng Li, Liliana De Lillo, Lee Empringham, C. Mark Johnson, University of Nottingham, GB; Andy Roberts, Robert Clarke, RAM Innovations, GB; Geoff Haynes, Inspirit Ventures, GB

### Power Electronics Topologies

- 26 Protection Schemes in Low-Voltage DC Shipboard Power Systems .....195**  
Seongil Kim, Drazen Dujic, EPFL – Ecole Polytechnique Fédérale de Lausanne, CH; Soo-Nam Kim, Hyundai Electric, ROK
- 27 Power Stage and Control Design of A 60-kV 60-kW Switching Power Supply for Industrial Electrostatic Precipitators .....202**  
Shengwen Fan, Yiqin Yuan, Zhenyu Shan, Pengyu Jia, Zhengxi Li, Yinghong Li, Yongchang Zhang, Guofeng Yuan, North China University of Technology, CN
- 28 Design of a three-phase 70 kW Current Source Inverter for Photovoltaic Applications Using a New 1.7 kV Full-SiC Voltage Bidirectional Power Module .....210**  
Luis Gabriel Alves Rodrigues, Jérémy Martin, Anthony Bier, Stéphane Catellani, Commissariat à l'Énergie Atomique et aux Énergies Alternatives, F; Jean-Paul Ferrieux, University Grenoble Alpes, F




### Multi-Level Converters

- 29 Modular Multilevel Converters as Active Filters to Mitigate Low Frequency Current Harmonics in Converter Fed Grid Applications .....218**  
Dennis Bräckle, Stefan Mersche, Mathias Schnarrenberger, Patrick Himmelmann, Marc Hiller, Karlsruhe Institute of Technology (KIT), D
- 30 MMC-Based High Power DC-DC Converter Employing Scott Transformer .....226**  
Stefan Milovanovic, Drazen Dujic, Power Electronics Laboratory, EPFL, CH
- 31 Experimental Validation of Three-Level Advanced-Active-Neutral-Point-Clamped Converter for Grid Operation .....233**  
Sidney Gierschner, Felix Kayser, David Hammes, Yves Hein, Hans-Günter Eckel, University of Rostock, D; Diemtar Krug, Siemens, D

## Energy Storage

- 32 Megawatt Scale Li-Ion Batteries Mounted in Opposition to Save Power During Test .....241**  
Younès Jaoui, Philippe Laflaquiere, Carlos Santaolalla, Cyril Monnoyer, Cedric Alnet, SAFT, F
- 33 A Battery Cell Emulator for Hardware in the Loop Tests of Reconfigurable Lithium-Ion and Post-Lithium Batteries .....245**  
Simon Bischof, Cem Küçük, Thomas Blank, Marc Weber, Karlsruhe Institute of Technology (KIT), D
- 34 Combined Sensor Minimal Cell-Monitoring and Active Inductive or Capacitive Cell-Balancing .....252**  
Constantinos Sourkounis, Philip Dost, Ruhr-University of Bochum, D

## High Power IGBT Devices

-  **35 A 6.5 kV 1000 A IGBT Module with Side Gate HiGT .....258**  
Hiroyuki Koguchi, Taiga Arai, Takayuki Kushima, Tatsuya Matsumoto, Hiroki Kawano, Takahiro Saiki, Tetsuo Oda, Hitachi Power Semiconductor Device, J; Masaki Shiraiishi, Hitachi, J
-   **36 Plasma-induced Diode Short-Circuit in Neutral-Point-Clamped Converters .....265**  
David Hammes, Jan Fuhrmann, Robin Schrader, Sidney Gierschner, Hans-Günter Eckel, University of Rostock, D; Dietmar Krug, Siemens, D
- 37 The Third Generation 6.5 kV HiPak2 Module Rated 1000 A and 150 °C .....273**  
Charalampos Papadopoulos, Boni Boksteen, Maxi Andenna, Elizabeth Buitrago, Samuel Hartmann, Sven Matthias, Chiara Corvasce, Arnost Kopta, Umamaheswara Vemulapati, Gontran Pâques, Raffael Schnell, Friedhelm Bauer, Daniel Prindle, Marco Bellini, Munaf Rahimo, ABB Switzerland, CH
- 38 Design and Development of an Integrated Power Module Used in Low Voltage DC/AC Hybrid Circuit Breaker .....281**  
Kenan Askan, Michael Bartonek, Eaton Industries, AT; Klaus Sobe, Infineon Technologies, AT
- 39 New 1200 V IGBT and Diode Technology with Improved Controllability for Superior Performance in Drives Application .....289**  
Christian R. Müller, Alexander Philippou, Christian Jäger, Max Seifert, Infineon Technologies, D; Antonio Vellei, Michael Fugger, Infineon Technologies, AT

## Converter Design and Integration

- 40 Fully Optimized Discrete Coupled Inductor DC/DC Converter as the TriMagiC Converter™ .....297**  
Mitsunao Fujimoto, Yutaka Naito, ALPS Electric, J
- 41 Ultra Compact 2 kW 12 V – 48 V Converter Using a 4-Phase Coupled Inductor .....303**  
Patrick Deck, Christian Peter Dick, Institute for Automation Engineering, TH Köln, D
- 42 Thermal Analysis of a Directly Liquid Cooled Silicon Carbide Resonant Inverter for High Voltage Generation .....311**  
Ulf Müter, Klaus F. Hoffmann, Helmut Schmidt University of the Federal Armed Forces Hamburg, D; Oliver Woywode, Jens Radvan, Philips Medical Systems DMC, D



- 43 Highly Integrated Two-Phase SiC Boost Converter with 3D Printed Fluid Coolers and 3D Printed Inductor Bobbins .....317**  
Arne Hendrik Wienhausen, Alexander Sewergin, Rik W. de Doncker, RWTH Aachen University, D

- 44 High Step-Up High-Frequency Zero-Voltage Switched GaN-Based Single-Stage Isolated DC-DC Converter for PV Integration and Future DC Grids .....325**  
Armin Jafari, Elison Matioli, POWERlab, EPFL, CH

### Control in Power Electronics



- 45 Control Scheme for Wide-Bandgap Motor Inverters with an Observer-Based Active Damped Sine Wave Filter .....331**  
Franz Maislinger, Hans Ertl, Technical University of Vienna, AT; Goran Stojcic, Florian Holzner, Christoph Lagler, B&R Industrial Automation, AT

- 46 Adaptive Frequency Control of DC-DC-Converters for Maximum Efficiency Using Artificial Neural Network .....340**  
Lukas Keuck, Arsalan Munir, Frank Schafmeister, Joachim Böcker, University of Paderborn, D

- 47 AC Input Current Distortions and Compensation Schemes of PFC Stages Working in Critical Conduction Mode .....348**  
Markus Schmid, Infineon Technologies, D

- 48 Adaptive and Robust Stabilization of Flyback Power Converters with Digital Control .....356**  
Gaetan Beneux, Louis Grimaud, Safran, F; Pierre Riedinger, Jamal Daafouz, SAFRAN-CRAN, F

- 49 Asymmetric Current Control of Grid Connected 3-Phase Cascaded H-Bridge Multilevel Inverter .....364**  
Taha Lahlou, Markus Herzog, Nagendra Ningappa Badiger, Hans-Georg Herzog, Technical University of Munich, D

### Gate Driver

- 50 IGBT Power Stage Delay Calibration is Minimizing Current Imbalance in Large Power Modules with Isolated Multiply Segmented Paralleled Half Bridges .....372**  
Sven Teuber, Marco Honsberg, Günter Katzenberger, Axel Kubitz, SEMIKRON Elektronik, D

- 51 Performance Comparison Between Voltage Source and Current Source Gate Drive Systems .....379**  
Wolfgang Frank, Infineon Technologies, D; Ziqing Zheng, Infineon Technologies, CN

- 52 High-Side Driver Supply With Reduced Coupling Capacitance .....384**  
Jens Friebe, Leibniz Universität Hannover, D; Oliver Prior, SMA Solar Technology, D; Marcin Kacki, SMA Magnetics, PL

- 53 An Isolated Voltage-Source Integrated SiC Gate Driver IC with a Slew Rate Adjusting for Gate-Resistance-Free .....392**  
Yasufumi Kawai, Yoshiharu Anda, Shuichi Nagai, Tsuguyasu Hatsuda, Noboru Negoro, Shingo Enomoto, Osamu Tabata, Songbaek Choe, Panasonic, J

- 54 A Gate Driver Approach using Inductive Feedback to Decrease the Turn-on Losses of Power Transistors .....396**  
Michael Ebli, Martin Pfost, Technical University of Dortmund, D



### Special Session: Passive Components

<b>55</b>	<b>Design and Optimization Method of PCB-Integrated Inductors for High-Frequency Converters</b> .....	<b>402</b>
	Ammar Chafi, Nadir Idir, Arnaud Videt, Thierry Duquesne, University of Lille – L2EP, F; Hassan Maher, LN2, Université de Sherbrooke, CA	
<b>56</b>	<b>Simulating the Parasitic Capacitance of Inductive Components</b> .....	<b>410</b>
	Stefan Scheffler, Jörn Schlieve, Stefan Weber, EPCOS, D	
<b>57</b>	<b>Future Winding for Next Power Electronic Generation</b> .....	<b>418</b>
	Dennis Kampen, BLOCK Transformatoren-Elektronik, D	
<b>58</b>	<b>Ripple Current Determination for Inductors in a DC/DC Converter Both With and Without Magnetic Bias</b> .....	<b>420</b>
	Tobias Appel, Daniel Benner, STS Spezial-Transformatoren Stockach, D	
<b>59</b>	<b>Development of Accelerated Testing of Thermal Degradation in Metallized Ceramic Substrates for SiC Power Modules</b> .....	<b>427</b>
	Hiroyuki Miyazaki, Hideki Hyuga, Hiroshi Sato, Hiroshi Yamaguchi, Kiyoshi Hirao, National Institute of Advanced Industrial Science and Technology (AIST), J; Shoji Iwakiri, Hideki Hirotsuru, Denka, J	

### SiC Devices II

<b>60</b>	<b>Beyond the Datasheet: Commercialization of 700 V – 1.7 kV SiC Devices with Exceptional Ruggedness for Automotive &amp; Industrial Applications</b> .....	<b>434</b>
	Avinash S. Kashyap, Amaury Gendron-Hansen, Dumitru Sdrulla, Bruce Odekirk, Dennis Meyer, William Brower, Changsoo Hong, Microsemi, USA	
<b>61</b>	<b>6.5-kV Full-SiC Power Module (HV100) with SBD-embedded SiC-MOSFETs</b> .....	<b>441</b>
	Jun-ichi Nakashima, Akinori Nishizawa, Tetsu Negishi, Shin-ichi Iura, Akihisa Fukumoto, Yoshiko Obiraki, Takeshi Oi, Yohei Mitsui, Hiroshi Nakatake, Yoshihiko Toyoda, Koutarou Kawahara, Shiro Hino, Hiroshi Watanabe, Mitsubishi Electric, J	
<b>62</b>	<b>Is an Antiparallel SiC-Schottky Diode Necessary? Calorimetric Analysis of SiC-MOSFETs Switching Behavior</b> .....	<b>448</b>
	Otto Kreuzer, Markus Billmann, Fraunhofer Institute IISB, D; Martin März, FAU Erlangen-Nuremberg, D	

### High Power IGBT System Applications

<b>63</b>	<b>A Test Bench for Thermal Characterization of IGBT Power Modules Over Mission Profiles</b> .....	<b>455</b>
	Christoph van der Broeck, Rik W. de Doncker, RWTH Aachen, D; Hao Zeng, Robert D. Lorenz, University of Wisconsin-Madison WEMPEC, USA	
<b>64</b>	<b>Floating Gate Method to Protect IGBT Module from Explosion in Traction Converters</b> .....	<b>463</b>
	Enea Bianda, Vinoth Kumar Sundaramoorthy, Gerold Knapp, Alexander Heinemann, ABB Switzerland, CH	
<b>65</b>	<b>A Condition Monitoring System for Power Semiconductors in Wind Energy Plants</b> .....	<b>470</b>
	Wilfried Holzke, Holger Groke, Alexander Brunko, Nando Kaminski, Bernd Orlik, University of Bremen, D	

## Advanced Packaging Technologies II

- 66 Sintering Cu Bonding Paste: Cycle Reliability and Applications .....477**  
Hideo Nakako, Yoshinori Ejiri, Chie Sugama, Yuki Kawana, Motohiro Negishi, Yuichi Yanaka, Dai Ishikawa, Hitachi Chemical, J
- 67 Selective Silver Sintering of Semiconductor Dies on PCB .....483**  
Fabian Dresel, Sigrid Zischler, Sebastian Letz, Andreas Schletz, Fraunhofer Institute IISB, D; Michael Novak, Continental, D
- 68 Feasibility of Copper-Based Ribbon Bonding as an Assembly Method for Advanced Power Modules .....491**  
Stefan Behrendt, Ronald Eisele, Katja Andersen, University of Applied Sciences Kiel D; Tao Xu, Christoph Luechinger, Kulicke & Soffa Industries, USA; Martin Becker, Andre Bastos Abibe, Robert Woehl, David Benning, Frank Osterwald, Danfoss Silicon Power, D

## HVDC Transmission Systems

- 69 Design of a Surge Arrester Based Load Commutation Switch for Hybrid HVDC Breakers and MVDC Breakers .....499**  
David Weiss, Mathias Duerr, Noemi Drack, Felix Kirchhoff, Philippe Maibach, ABB Switzerland, CH; Arman Hassanoor, ABB China, CN
- 70 Fault Discrimination in Bipolar HVDC MTS Equipped with Bus Bar Breakers .....505**  
Max Görtz, Rene Sander, Simon Wenig, Wolf Schulze, Michael Suriyah, Thomas Leibfried, Karlsruhe Institute of Technology (KIT), D
- 71 An HVDC Current Flow Controller for Multi-Terminal Grids .....513**  
Viktor Hofmann, Mark-M. Bakran, University of Bayreuth, D

## Software Tools and Applications

- 72 S-parameter Based Simulation Modeling a Power Module Independent of Measurement Data .....522**  
Junichi Kashiwagi, Hiroyuki Sakairi, Naotaka Kuroda, Hirotaka Otake, Ken Nakahara, ROHM, J
- 73 Electro-Thermal Simulation for Predicting the Temperature of SiC Dies in the Power Module of a High Frequency Operating Power Converter .....525**  
Yohei Nakamura, Hirotaka Otake, Yusuke Nakakohara, Hiroyuki Sakairi, Naotaka Kuroda, Ken Nakahara, ROHM, J; Tristan M. Evans, University of Arkansas, USA
- 74 Comparison of Dynamic Performance of a Lab-Scale Modular Multilevel Converter and its Equivalent Model for Real-Time Simulation .....529**  
Nikola Stankovic, Opal-RT Europe, F; Jerome Rivest, Wei Li, Jean Belanger, Opal-RT Technologies, CA

## Reliability SiC Devices

- 75 Practical Aspects and Body Diode Robustness of a 1200 V SiC Trench MOSFET .....536**  
Thomas Basler, Daniel Heer, Dethard Peters, Reinhold Schörner, Infineon Technologies, D; Thomas Aichinger, Infineon Technologies, AT



<b>76</b>	<b>High Dynamic Stress on SiC Trench MOSFET Body Diodes and their Behaviour</b> .....	<b>543</b>
	Andreas März, Teresa Bertelshofer, Mark-M. Bakran, University of Bayreuth, D	
<b>77</b>	<b>Reliability and Ruggedness of SiC Trench MOSFETs for Long-Term Applications in Humid Environment</b> .....	<b>551</b>
	Ingo Voss, Thomas Basler, Peter Friedrichs, Roland Rupp, Infineon Technologies, D; Thomas Aichinger, Infineon Technologies, AT	
<b>78</b>	<b>Investigation on Reliability of SiC MOSFET Under Long-Term Extreme Operating Conditions</b> .....	<b>555</b>
	Tien Anh Nguyen, Nidhal Boucenna, Denis Labrousse, Gérard Chaplier, Stéphane Lefebvre, SATIE-CNAM, F; Stéphane Azzopardi, Safran TECH, F	
<b>79</b>	<b>High Humidity, High Temperature and High Voltage Reverse Bias – A Relevant Test for Industrial Applications</b> .....	<b>563</b>
	Joni Jormanainen, Jonny Ingman, Aleks Vulli, ABB Oy, FI; Elena Mengotti, Thiago Batista Soeiro, Enea Bianda, David Baumann, Thomas Friedli, Alexander Heinemann, ABB Switzerland, CH	

### Power Modules & Smart Driver

<b>80</b>	<b>Impact of Load Profiles on Power Module Design – a Detailed Analysis Based on 7th Generation of IGBT and Diode Technology</b> .....	<b>570</b>
	Stefan Buschhorn, Anastasia Brodt, André Lenze, Alexander Philippou, Christian Jäger, Johannes Laven, Benjamin Sahan, Christian Müller, Infineon Technologies, D	
<b>81</b>	<b>A Novel Insulation Technology for Gate Drivers</b> .....	<b>578</b>
	Karsten Fink, Andreas Volke, Power Integrations, D; Matthias Kurth, Michel Graby, Power Integrations, CH	
<b>82</b>	<b>Directly Cooled HybridPACK Power Modules with Ribbon Bonded Cooling Structures</b> .....	<b>582</b>
	Andre Uhlemann, Erwin Hymon, Infineon Technologies, D	
<b>83</b>	<b>Enhanced Module Design with DPD Technology</b> .....	<b>588</b>
	Roberto Bellu, Christian Göbl, Andreas Maul, Clemens Vennebusch, SEMIKRON Elektronik, D	
<b>84</b>	<b>Direct 2-Way Coupled Electro-Thermal Simulation of Temperature and Current Distribution in Power Devices</b> .....	<b>593</b>
	Marina Montaine, Uwe Scheuermann, SEMIKRON Elektronik, D; Martin Hanke, CADFEM, D	

### Reverse Conducting IGBT's

<b>85</b>	<b>Short-Circuit Behavior of 6.5 kV RC-IGBT</b> .....	<b>601</b>
	Holger Wiencke, Daniel Lexow, Hans-Günter Eckel, University of Rostock, D	
<b>86</b>	<b>New Transfer Mold SMD Type IPM with Integrated RC-IGBT, Bootstrap Diode and Capacitor</b> .....	<b>607</b>
	Yazhe Wang, Maki Hasegawa, Mitsubishi Electric Corporation Power Device Works, J	
<b>87</b>	<b>The Series of 7th-Generation “X Series” RC-IGBT Modules for Industrial Applications</b> .....	<b>611</b>
	Akio Yamano, Hiroaki Ichikawa, Misaki Takahashi, Toru Ajiki, Yuichi Onozawa, Seiichi Takahashi, Makoto Isozaki, Soichi Okita, Yasuyuki Kobayashi, Osamu Ikawa, Fuji Electric, J	

- 88 4.5 kV Rupture Resistant Press Pack IEGT .....619**  
Raita Kotani, Tetsuya Nitta, Naoto Tsukamoto, Hideaki Kitazawa, Motoaki Kitagawa, Tomohiro Kawano, Toshiba, J; Georges Tchouangue, Toshiba, D
- 89 New Low Loss Phase Control Thyristors for Medium Current UHVDC Transmission .....623**  
Sascha Populoh, Chunlei Liu, Marco Bellini, Kenan Tugan, Urban Meier, Jan Vobecky, ABB Switzerland, CH

### High Frequency Converters

- 90 Optimisation of an Integrated Bidirectional Interleaved Single-Phase Power Factor Corrector .....627**  
Johan Le Lesle, Rémy Caillaud, Nicolas Degrenne, Roberto Mrad, Stefan Mollov, Mitsubishi Electric R&D Centre, F; Florent Morel, Cyril Buttay, Christian Vollaire, Laboratoire Ampère, F
- 91 Multi-MHz LED Drivers: Design for Lifetime and Reliability .....635**  
Riccardo Pittini, Thomas Andersen, Toke M. Andersen, Mickey Madsen, Martin Rødgaard, Jakob Mønster, Nordic Power Converters, DK
- 92 High-Frequency and High-Density Design of all GaN Power Supply Unit .....642**  
Ruiyang Yu, Qingyun Huang, Tianxiang Chen, Alex Q. Huang, University of Texas at Austin, USA; Tom Ribarich, Navitas Semiconductor, USA
- 93 Comparison Between an Interleaved Boost Converter Using Si MOSFETs Versus GaN HEMTs .....647**  
Simon Ravyts, Mauricio Dalla Vecchia, Jeroen Zwysen, Giel van den Broeck, Johan Driesen, KULeuven, BE
- 94 A Novel AC Direct Linear LED Driver with Unity Power Factor, Low Input Current THD, Low Light Flicker and Low Profile .....655**  
Jie Fu, Gang Wang, Shan Wang, Zhiquan Chen, Liang Shi, Philips Lighting Research Center, CN

### GaN Devices

- 95 High Power Nanosecond Pulse Laser Driver Using an GaN FET .....662**  
John Glaser, Efficient Power Conversion (EPC) Corporation, USA
- 97 Towards Highly-Integrated High-Voltage Multi-MHz GaN-on-Si Power ICs and Modules .....670**  
Stefan Moench, Oliver Ambacher, Richard Reiner, Beatrix Weiss, Patrick Waltereit, Rüdiger Quay, Fraunhofer-Institute IAF, D; Thomas Kaden, Robert Bosch, D; Ingmar Kalfass, University of Stuttgart, D
- 98 6.78 MHz Multi Amplifier and Transmit Coil eGaN® FET based Class-E Wireless Power System Evaluation .....678**  
Michael de Rooij, Yuanzhe Zhang, Efficient Power Conversion (EPC), USA

### System Reliability

- 99 Partial Discharge Measurement in a Motor Winding Fed by a SiC Inverter – How Critical is High dV/dt Really? .....685**  
Marco Denk, Mark M. Bakran, University of Bayreuth, D
- 100 Evaluation of Ag-sinter and CuSn-TLP Based Joining Technologies on Lead Frame .....691**  
Alexander Otto, Tim Schröder, Rainer Dudek, Mario Baum, Ralf Döring, Sven Rzepka, Wei-Shan Wang, Maik Wiemer, Jyothi Jennifer Kurian, Fraunhofer-Institute ENAS, D; Kei Murayama, Kiyoshi Oi, Tetsuya Koyama, Shinko Electric Industires, J

- 101 On-line Health Monitoring of Wire-Bonded IGBT Power Modules using On-State Voltage at Zero-Temperature-Coefficient .....699**  
Nicolas Degrenne, Stefan Mollov, Mitsubishi Electric R&D Centre Europe, F
- 102 First Results of Development of a Lifetime Model for Transfer Molded Discrete Power Devices .....706**  
Guang Zeng, Oliver Wenzel, Josef Lutz, Chemnitz University of Technology, D; Ludger Borucki, Oliver Schilling, Infineon Technologies, D

## Power Converters



- 103 25 kW High Power Resonant Inverter Operating at 2.5 MHz based on SiC SMD Phase-Leg Modules .....714**  
Fabian Denk, Karsten Haehre, Christoph Simon, Santiago Eizaguirre, Michael Heindinger, Rainer Kling, Wolfgang Heering, Karlsruhe Institute of Technology (KIT), D

- 104 A Trans-Linked 5-kW Inverter Using SiC MOSFETs to Achieve Fan-less Operation .....721**  
Tatsuya Miyazaki, Hirota Otake, Yusuke Nakahara, Ken Nakahara, ROHM, J; Mamoru Tsuruya, Power Assist Technology, J
- 105 High Power Constant Current Class EF2 GaN Power Amplifier for AirFuel Magnetic Resonance Wire-Less Power Transfer Systems .....724**  
Tiefeng Shi, Paul Wiener, GaN Systems, USA
- 106 System Efficiency and Power Density Comparison of Voltage-Source Based DC-Link and Matrix Converters for Highly Integrated Electric Motor Drives .....728**  
Rüdiger Schwendemann, Marc Hiller, Karlsruher Institute of Technology (KIT), D; Boris Janjic, KSB SE, D

## Advanced Sensors

- 107 Closed-Loop Hall Sensors with Near Fluxgate Performance for Residual Current Measurement in Photovoltaic Systems .....736**  
Stéphan Trombert, LEM Switzerland, CH
- 108 Evaluation of Overall Accuracy of New Current Sensing Concepts in Comparison to State-of-the-Art Methods .....744**  
Frank Lautner, Mark M. Bakran, University of Bayreuth, D
- 109 Design and Implementation of an Integrated Current Sensor for a Gallium Nitride Half-Bridge .....752**  
Janes Walter, Javier Acuna, Ingmar Kallfass, University of Stuttgart, D
- 110 Utilization of Parasitic Luminescence from Power Semiconductor Devices for Current Sensing .....760**  
Jonathan Winkler, Jan Homoth, Robert Bosch, D; Ingmar Kallfass, University of Stuttgart, D

## MOSFET and IGBT

- 111 A New MOSFET Intelligent Power Module for Low Power Motor Drive Applications .....768**  
Jaewook Lee, Junbae Lee, Daewoong Chung, Infineon Technologies Power Semitech, ROK

<b>112 High Voltage Semiconductor Switch on the Base Of RCRSD for Bipolar Power Current Pulse Commutation .....</b>	<b>771</b>
Alexey Grishanin, Alexey Khapugin, Valentin A. Martynenko, Vyacheslav Muskatinev, Vyacheslav Eliseev, Oleg Frolov, JSC Electrovipryamitel, RU; Sergey Korotkov, Ioffe Physico-Technical Institute, RU; Igor Galakhov, Vladimir Osin, Institute of Laser-Physical Researches, RU	
<b>113 IGCT Switching Behaviour Under Low Current Conditions .....</b>	<b>777</b>
Dragan Stamenkovic, Drazen Dujic, EPFL – Ecole Polytechnique Fédérale de Lausanne, CH; Umamaheswara Reddy Vemulapati, Munaf Rahimo, Thomas Stiasny, ABB Semiconductors, CH	
<b>114 LV100 High Voltage Dual Package in Paralleling Operation .....</b>	<b>783</b>
Ryo Tsuda, Nils Soltau, Eugen Wiesner, Eckhard Thal, Mitsubishi Electric Europe, D; Shinichi Iura, Tetsu Negishi, Mitsubishi Electric Corporation, J	
<b>115 MOSFET Technologies for Auxiliary DC-DC Converters .....</b>	<b>789</b>
Filippo Scrimizzi, Filadelfo Fusillo, STMicroelectronics, I	
<b>116 Evaluation of Miller Capacitance Depending on Drain-Source Voltage when SJ HV Power MOSFETs are in Reverse Mode .....</b>	<b>793</b>
Carmelo Parisi, Domenico Murabito, Valeria Cinnera Martino, Yosef Damante, Antonio Giuseppe Grimaldi, STMicroelectronics, I; Giuseppe Consentino, University of Calabria, I	
<b>117 Dynamic Current Sharing and Gate Feedback During Turn-OFF of Paralleled IGBTs .....</b>	<b>798</b>
Robin Schrader, Patrick Münster, Hans-Günter Eckel, University of Rostock, D	
<b>118 SuperJunction Power Device Evolution: Characteristics Analysis and Performance Comparison of MDmesh™ M2 and MDmesh™ M6 Technologies .....</b>	<b>805</b>
Antonino Gaito, Maurizio Melito, Santina Leo, STMicroelectronics, I	
<b>119 Characterization of Voltage Divergence in Series Connected SiC Trench MOSFETs and Si IGBTs .....</b>	<b>810</b>
Zarina Davletzhanova, Olayiwola Alatise, Jose Ortiz Gonzalez, Tianxiang Dai, Roozbeh Bonyadi, University of Warwick, GB	
<b>120 SiC and Silicon MOSFET Solution for High Frequency DC-AC Converters .....</b>	<b>817</b>
Luigi Abbatelli, Cristiano Gianluca Stella, Giuseppe Catalisano, STMicroelectronics, I	
<b>121 Short Circuit Robustness Improvement by FEM Simulation on IGBT .....</b>	<b>821</b>
Daniela Cavallaro, Rosario Greco, Gaetano Bazzano, STMicroelectronics, I	
<b>122 A New Combined <math>V_{GE}</math> and <math>V_{CE}</math> Based Short-Circuit Detection for High-<math>I_{C,desat}</math> HV-IGBTs and RC-IGBTs .....</b>	<b>825</b>
Julian da Cunha, David Hammes, Jan Fuhrmann, Daniel Lexow, Hans-Günter Eckel, University of Rostock, D	

## SiC Devices

<b>123 Analog Based High Efficiency 2 KW Totem Pole PFC Converter Using Surface Mount SiC MOSFET's .....</b>	<b>833</b>
Jianwen Shao, Guy Moxey, Cree, USA; Binod Agrawal, Venkata Subash Bathula, Navneet Mangal, Cree, IN	
<b>124 Switching Pattern and Performance Characterization for “SiC+Si” Hybrid Switch .....</b>	<b>839</b>
Haihong Qin, Qiang Xiu, Dan Wang, Shishan Wang, Nanjing University of Aeronautics and Astronautics, C; Chaohui Zhao, Shanghai DianJi University, CN	
<b>125 Driver Integrated Fault-Tolerant Reconfiguration after Short-On Failures of a SiC MOSFET ANPC Inverter Phase .....</b>	<b>845</b>
Michael Gleißner, Teresa Bertelshofer, Mark-M. Bakran, University of Bayreuth, D	

<b>126 SiC Effect on Surge Voltage Distribution in Large Electrical Machines .....</b>	<b>853</b>
Robert Maier, Mark-M. Bakran, University of Bayreuth, D	
<b>127 Junction Temperature Measurement of SiC MOSFETs: Straightforward as it Seems? .....</b>	<b>860</b>
Tobias Kestler, Mark-M. Bakran, University of Bayreuth, D	
<b>128 In-Depth Study of Short-Circuit Robustness and Protection of 1200 V SiC MOSFETs .....</b>	<b>866</b>
Xuning Zhang, Levi Gant, Gin Sheh, Sujit Banerjee, Monolith Semiconductor, USA	
<b>129 Avalanche Rugged Low On-Resistance 1200 V SiC MOSFETs With Long-Term Stability .....</b>	<b>873</b>
Kwangwon Lee, ON Semiconductor, KR, Martin Domeij, Jimmy Franchi, Benedetto Buono, Fredrik Allerstam, ON Semiconductor, SE; Thomas Neyer, ON Semiconductor, D	
<b>130 High Performance 4H-SiC MOSFETs with Optimum Design of Active Cell and Re-Oxidation Process .....</b>	<b>879</b>
Toshikazu Tanioka, Yuji Ebiike, Yasunori Oritsuki, Masayuki Imaizumi, Masayoshi Tarutani, Mitsubishi Electric Corporation, J	
<b>131 Derating of Parallel SiC MOSFETs Considering Switching Imbalances .....</b>	<b>885</b>
Teresa Bertelshofer, Andreas März, Mark-M. Bakran, University of Bayreuth, D	
<b>132 Commutation Characteristics During Switching of Hybrid SiC and Si Configurations .....</b>	<b>893</b>
Michael Schütt, Hans-Günter Eckel, University of Rostock, D	
<b>133 Current Sharing During Unipolar and Bipolar Operation of SiC JBS Diodes .....</b>	<b>898</b>
Thomas Barbieri, Adam Barkley, James Solovey, Edward van Brunt, Edgar Ayerbe, Wolfspeed, USA	

## GaN Devices and Applications

<b>135 Application of GaN-GITs in a Single-Phase T-Type Inverter .....</b>	<b>905</b>
Carsten Kuring, Jan Böcker, Sibylle Dieckerhoff, Jonas Lenth, Tino Kahl, Technical University of Berlin, D	
<b>136 S-Parameter Characterization of GaN HEMT Power Transistors for High Frequency Modeling .....</b>	<b>913</b>
Loris Pace, Arnaud Videt, Nadir Idir, University of Lille – L2EP, F; Nicolas Defrance, Jean-Claude Dejaeger, University of Lille – IEMN, F	
<b>137 650 V E-Mode GaN HEMT Switching at 1 MHz for Travel Adapter Applications .....</b>	<b>921</b>
Ann Starks, Zhiyang Chen, Mike Cargile, ON Semiconductor, USA	
<b>138 Power p-GaN HEMT Under Unclamped Inductive Switching Conditions .....</b>	<b>929</b>
Juraj Marek, Alexander Šatka, Martin Jagelka, Aleš Chvála, Patrik Příbytný, Martin Donoval, Daniel Donoval, Slovak Technical University in Bratislava, SK	
<b>139 Designing High-Density Power Solutions with GaN .....</b>	<b>934</b>
Paul Brohlin, Masoud Beheshti, Texas Instruments, USA	
<b>140 Inverse Thermal Model of Temperature-to-Power Mapping for eGaN Systems .....</b>	<b>939</b>
Shuangfeng Zhang, Eric Laboure, University of Paris, F; Denis Labrousse, Stéphane Lefebvre, ENS Cachan – SATIE, F	
<b>141 High Performance Thermal Solution for High Power eGaN® FET Based Power Converters .....</b>	<b>944</b>
Michael de Rooij, Yuanzhe Zhang, David Reusch, Efficient Power Conversion (EPC) Corporation, USA; Sriram Chandrasekaran, Raytheon, USA	

- 142 Wafer Level Embedding Technology for Packaging of Planar GaN Half-Bridge Module in High Power Density Conversion Applications .....951**  
Charles-Alix Manier, Kirill Klein, Hermann Oppermann, Klaus-Dieter Lang, Felix Wüst, Robert Gernhardt, Fraunhofer-Institute IZM, D; Sophie Andzouana, Radoslava Mitova, Schneider Electric, F; Philippe Cussac, CIRTEM, F
- 143 Monolithic GaN Power ICs Enable High Density High Frequency 3.2 KW AC-DC Rectifier .....959**  
Tom Ribarich, Dan Kinzer, Navitas Semiconductor, USA; Ruiyang Yu, Qingyun Huang, Alex Q. Huang, University of Texas at Austin, USA
- 144 Experimental Study on Gate Drive Influence to the 650 V GaN E-HEMT .....963**  
Zhang Yi, Teng Liu, Yifan Tan, Cai Chen, Yong Kang, Huazhong University of Science and Technology, CN

### SiC Power Modules

- 145 Switching Behavior of SiC-MOSFETs in High Power Modules .....969**  
Florian Störmer, Hans-Günter Eckel, University of Rostock, D; Franz-Josef Niedernostheide, Frank Pfirsch, Infineon Technologies, D
- 146 The Challenges of Using SiC MOSFET-Based Power Modules for Solar Inverters .....975**  
Matthias Tauer, Vincotech, D
- 147 Low Inductive SiC Power Module Design Using Ceramic Multilayer Substrates .....980**  
Thomas Huber, Alexander Kleimaier, University of Applied Sciences Landshut, D; Sebastian Polster, Olivier Mathieu, Rogers, D
- 148 Very Low Stray Inductance, High Frequency 1200 V\_ 2 mOhms Full SiC MOSFET Phase Leg Module .....988**  
Serge Bontemps, Pierre Laurent Doumergue, Microsemi Power Module Products, F
- 149 Comparative Study of Full SiC Power Module in 1 MHz, 600 V, 50 A Switching Operation .....996**  
Kei Hayashi, Tsuyoshi Funaki, Osaka University, J; Hisato Michikoshi, Kenji Fukuda, National Institute of Advanced Industrial Science and Technology, J
- 150 3.3 kV SiC Hybrid Module with High Power Next Core (HPnC) Package .....1001**  
Lukas Kleingrothe, Fuji Electric, D; Yusuke Sekino, Susumu Iwamoto, Akira Iso, Hideaki Kakiki, Yuichi Harada, Osamu Ikawa, Tomohiro Moriya, Fuji Electric, J
- 151 High Reliable 1700 V Full SiC Power Module .....1009**  
Kenji Hayashi, Yoshihisa Tsukamoto, Masaaki Matsuo, Masashi Hayashiguchi, Motohiro Ando, ROHM, J
- 152 Analysis of 1200 V Si-SiC-Hybrid Switches for Resonant Applications .....1012**  
Michael Meissner, Sebastian Fahlbusch, Daniel Lühke, Klaus F. Hoffmann, Helmut Schmidt University, D
- 154 Sintering Cu Paste Die-Attach for High TJ Power Devices .....1020**  
Shijo Nagao, Yue Gao, Akio Shimoyama, Katsuaki Suganuma, Osaka University, J; Shinichi Yamauchi, Takahiko Sakaue, Yoichi Kamikoriyama, Mitsui Mining & Smelting, J



## Advanced Power Modules


<b>155 Influence of Auxiliary Gate and Emitter Connections on Short Circuit Behaviour of Multichip IGBT Modules .....</b>	<b>1023</b>
Helong Li, Chunlin Zhu, Paul Mumby-Croft, Yafei Wang, Daohui Li, Yangang Wang, Dynex Semiconductor, GB; Xiaoping Dai, CRRC Times Electric, CN	
<b>156 Impact of I<sup>2</sup>t Capability of RC-IGBT and Leadframe Combined Structure in xEV Active Short Circuit Survival .....</b>	<b>1028</b>
Hayato Nakano, Akihiro Osawa, Keiichi Higuchi, Akio Kitamura, Daisuke Inoue, Souichi Yoshida, Hiromichi Gohara, Masahito Otsuki, Fuji Electric, J	
<b>157 New Developed 3.3 kV / 1500 A IGBT Module .....</b>	<b>1033</b>
Daohui Li, Ariful Islam, Yangang Wang, Fang Qi, Matthew Packwood, Paul Mumby-Croft, Dynex Semiconductor, GB; Xiaoping Dai, Haihui Luo, Guoyou Liu, Wei Zhou, CRRC Times Electric, CN	
<b>158 Newly Developed 7th Generation 1,700 V IGBT Module Product Family for Industrial Application .....</b>	<b>1038</b>
Takuya Yamamoto, Shinichi Yoshiwatari, Osamu Ikawa, Souichi Okita, D. Nagai, S. Miyashita, Y. Sakurai, Y. Onozawa, T. Ito, Fuji Electric, J; Thomas Heinzl, Fuji Electric, D	
<b>159 Analytical Modelling of Dynamic Power Losses Inside Power Modules for 2-Level Inverters ....</b>	<b>1044</b>
Arne Bieler, Ole Mühlfeld, Danfoss Silicon Power, D	
<b>160 Failure Protection in Power Modules with Auxiliary-Emitter Bond-Wires .....</b>	<b>1051</b>
Nick Baker, Francesco Iannuzzo, Aalborg University, DK	
<b>161 An Efficient Active Mains Rectifier Bridge Based on Bipolar Technology .....</b>	<b>1057</b>
Nick Koper, WeEn Semiconductors, NL; John Wood, Silicon Contact, UK	
<b>162 Development of New 600 V Smart Power Module for Home Appliances Motor Drive Application .....</b>	<b>1062</b>
Samuell Shin, Bumseung Jin, Kinam Song, Sewoong Oh, Thomas Yim, ON Semiconductor, ROK	

## DC-DC Converters

<b>163 Implementation of an Adaptive Dead Time in Resonant Converters .....</b>	<b>1068</b>
Christian Oeder, Nikolas Foerster, Thomas Dürbaum, Friedrich Alexander University of Erlangen, D	
<b>164 Modified Basic DC-DC Converters .....</b>	<b>1076</b>
Felix Himmelstoss, Karl Edlmoser, Technikum Vienna, AT	
<b>165 GaN Based Multilevel Intermediate Bus Converter for 48 V Server Applications .....</b>	<b>1084</b>
David Reusch, Suvankar Biswas, Michael de Rooij, Efficient Power Conversion (EPC), USA	
<b>166 A FPGA-Based Algorithm for Soft Switched DC-DC Converters with a Variable Transmission Path .....</b>	<b>1092</b>
Lukas Göbel, Ansgar Ackva, Sebastian Raab, University of Applied Sciences Würzburg-Schweinfurt, D	
<b>167 Compact Bidirectional GaN Buck-Boost Converter for Negative Rail Supply in Bipolar DC-Grids .....</b>	<b>1098</b>
Sebastian Klötzer, Sebastian Fahlbusch, Ulf Mütter, Klaus F. Hoffmann, Helmut Schmidt University, D	
<b>168 Exact Analytical Solution of the Peak Gain for the LLC Resonant Converter .....</b>	<b>1106</b>
Markus Barwig, Christian Oeder, Manfred Albach, Friedrich Alexander University of Erlangen, D	
<b>169 GaN Buck Converter in CCM with Optimized High Frequency Inductors .....</b>	<b>1113</b>
Sven Bolte, Norbert Fröhleke, Joachim Böcker, University of Paderborn, D	

- 170 Modelling of a Bi-Directional Converter from a Power Supplying System With Application in Radio Communication Systems .....1119**  
Ivan Nedyalkov, University of Telecommunications and Post, BG; Dimitar Arnaudov, Nikolay Hinov, Technical University of Sofia, BG
- 171 A Bidirectional Quasi-Z-Source Based DC-DC Converter .....1127**  
Yuba Raj Kafle, Graham E. Town, Macquarie University, AU

### Traction, Ship, Aircraft

- 172 Humidity in Traction Converters .....1132**  
Fabian Quast, Andreas Nagel, Siemens, D
- 173 New Traction Converter with Low Inductive High-Voltage Half Bridge IGBT Module .....1139**  
Bernd Laska, Jan Weigel, Siemens, D; Sven Buchholz, Waleri Brekel, Matthias Wissen, Thomas Gutt, Infineon Technologies, D; Patrick Münster, Till-Mathis Plötz, Hans-Günter Eckel, Robin Schrader, Ingmar Kirchner, University of Rostock, D
- 174 Nanocrystalline Cores for Common Mode Current Suppression in Electrical Ship Propulsion System – a Case Study .....1146**  
Wulf Günther, Acal BFi Germany, D; Zoran Malbasic, Alewijnse Marine Nijmegen, NL
- 175 Discrete 1200 V SiC MOSFETs – SMD Package Benefits and Impacts of Multiple Device and Circuit Parameters Mismatch in High Power Parallel Applications .....1151**  
Rajagopalan Jagannathan, Hans-Peter Hoenes, Tushar Duggal, Marco Atzeri, ON Semiconductor, D
- 176 High-Dynamic High-Power E-Motor Emulator for Power Electronic Testing .....1157**  
Sebastian Liebig, Alexander Schmitt, Horst Hammerer, SET Power Systems, D
- 177 New Approach of Smart Hybrid Power Module Dedicated to Aircraft Electro-Mechanical Actuators up to 20 kW .....1162**  
Alain Calmels, Julien Richer, Microsemi Power Module Products, F; Shane O'Donnell, Microsemi, IR
-  **178 Diagnostic Technique for Traction Motor Insulation Condition Monitoring by Transient Signal Assessment .....1170**  
Markus Vogelsberger, Martin Bazant, Bombardier Transportation Austria, AT; Clemens Zöller, Hans Ertl, Thomas M. Wolbank, Technical University of Vienna, AT

### Control, Intelligent Motion

- 179 Modelling of Inverter Nonlinear Effects .....1178**  
Simon Wiedemann, Ralph M. Kennel, Technical University of Munich, D; Anton H. Tamas, MACCON, D
- 180 Self-Commissioning of the Current Control Loop in AC Drives .....1184**  
Simon Wiedemann, Ralph M. Kennel, Technical University of Munich, D
- 181 Sensorless Position Estimation for an Externally Excited Synchronous Machine over the Whole Speed Range .....1192**  
Johannes Schuster, Vasken Ketchedjian, Jörg Roth-Stielow, University of Stuttgart, D
- 182 VSI with Sinusoidal Voltages for an Enhanced Sensorless Control of the Induction Machine ..... 1199**  
Harith Al-Badrani, Simon Feuersänger, Mario Pacas, University of Siegen, D

<b>183 Simplified Wide Speed-Range Sensorless Control Scheme for a Permanent Magnet Synchronous Machine .....</b>	<b>1206</b>
Van Trang Phung, Mario Pacas, University of Siegen, D	
<b>184 A Stacked 7-Level Common Mode Voltage Eliminated Inverter Scheme with Single DC-link for Open-End Induction Motor Drive .....</b>	<b>1214</b>
Apurv Kumar Yadav, Kumarukuttan Nair Gopakumar, Krishna Raj Ramachandran Potti, Loganathan Umanand, Indian Institute of Science, IN; Kouki Matsuse, Hisao Kubota, Meiji University, J	
<b>185 Energy Optimal Motion and Rotor Flux Trajectories for an Induction Motor Drive .....</b>	<b>1221</b>
Gunar Steinborn, Wilfried Hofmann, Technical University of Dresden, D	
<b>186 Controller Synthesis and Testing in a 48 V System Based on Physical Models .....</b>	<b>1228</b>
Sabin Carpiuc, The MathWorks, GB	
<b>187 Modeling and Analyzing the Stability of an Induction Motor Drive System Using an Output LC Filter .....</b>	<b>1235</b>
Pascal Combes, Al Kassem Jebai, Schneider Electric, F	
<b>188 Synchronization of Multi-Axis Motion Control Over Real-Time Networks .....</b>	<b>1243</b>
Jens Sorensen, Analog Devices, USA; Christian Aaen, Dara O'Sullivan, Analog Devices, IR	
<b>189 Lean and Fast Fieldbus based Safety Functionality for Drives in Automation .....</b>	<b>1250</b>
Jens Onno Krahn, Adin Basic, Technical University of Cologne, D	

## Renewable Energy and Power Transmission

<b>190 A Sliding-Mode-Observer for Encoderless Direct Model Predictive Control of PMSGs .....</b>	<b>1257</b>
Mohamed Abdelrahem, Philipp Catterfeld, Christoph Hackl, Ralph Kennel, Technical University of Munich, D	
<b>191 Wind Turbine Nacelle Test Bench Using an Optimized Torque Control and an Aerodynamic Real Time Model .....</b>	<b>1265</b>
Sören Behrens, Johannes Adler, Bernd Orlik, University of Bremen, D; Holger Raffel, Bremen Center of Mechatronics, D; Holger Schlöcker, SIT, D	
<b>192 Wind Turbine for Underground Subway Stations .....</b>	<b>1273</b>
Lilia Galai Dol, Jose Luis Cardassi, Efficacy, F; Alexandre De Bernardinis, IFSTTAR, F	
<b>193 Assisting passive anti-islanding proposal for Voltage-Controlled Voltage-Source-Inverters .....</b>	<b>1279</b>
Cristian Chillón-Antón, Marc Llonch-Masachs, Daniel Heredero-Peris, Daniel Montesinos-Miracle, Universitat Politècnica de Catalunya CITCEA-UPC, ES; Marc Pagès-Giménez, Teknocea, ES	
<b>194 Evaluation of DC-DC-Converter Impedance Passivity Using Pseudo-Random Test Signals ...</b>	<b>1287</b>
Leopold Ott, Yunchao Han, Bernd Wunder, Fraunhofer Institute IISB, D; Martin März, University Erlangen-Nuremberg, D; Fabian Bodensteiner, Blacbird Technologies, D	
<b>195 Solving Isolation- and Power Supply Problems for Current Monitoring in High Voltage Power Line Application .....</b>	<b>1295</b>
Bernhard Strzalkowski, Analog Devices, D; Kelven Mo, Analog Devices, CN	
<b>196 Zero Vector Placement Strategies in Space Vector Modulation of Inverters for UPS Applications .....</b>	<b>1298</b>
Lorenzo Giuntini, GE Consumer & Industrial, CH	

## Passive Components, Sensors, Diagnostics

<b>197</b>	<b>Advanced Solutions in Over-Current Protection of HvdC Circuit of Battery-Powered Electric Vehicle</b> .....	<b>1305</b>
	Mitja Koprivsek, ETI Elektroelement, SI	
<b>198</b>	<b>Inductive Power Transfer Systems for Rotating Applications</b> .....	<b>1309</b>
	Nikolay Madzharov, Raycho Ilarionov, Valeri Petkov, Lyudmil Petkov, Technical University, Gabrovo, BG	
<b>199</b>	<b>Coupled-Inductors Losses Modelling for Size and Weight Optimization Process Avoiding Time-Consuming Co-Simulations</b> .....	<b>1317</b>
	Leyla Arioua, Menouar Ameziani, VEDECOM, F	
<b>200</b>	<b>Enlarging the Standard Permeability Set of Powder E-Cores by Combination of Different Perm Core-Halves</b> .....	<b>1323</b>
	Paul Winkler, Wulf Günther, Acal BFi Germany, D	
<b>201</b>	<b>Guideline for Hysteresis Curve Measurements with Arbitrary Excitation: Pitfalls to Avoid and Practices to Follow</b> .....	<b>1328</b>
	Erika Stenglein, Daniel Kübrich, Manfred Albach, Thomas Dürbaum, Friedrich Alexander University of Erlangen, D	
<b>202</b>	<b>Comparing Inductive Components for Different Boost Converter Topologies in a PV System</b> .....	<b>1336</b>
	Michael Schmidhuber, Christian Reichhart, SUMIDA Components & Modules, D; Marco Jung, Fabian Schnabel, Fraunhofer IEE, D	
<b>203</b>	<b>Linear Machine with a Magnetic-Coupled Structure Based on the Transverse Flux Technology</b> .....	<b>1341</b>
	Jannik Ulbrich, Alexander Norbach, Bernd Orlik, Holger Raffel, University of Bremen, D	
<b>204</b>	<b>Wide Bandwidth Current Sensor Combining a Coreless Current Transformer and TMR Sensors</b> .....	<b>1349</b>
	Nathan Tröster, Johannes Ruthardt, Maximilian Nitzsche, Jörg Roth-Stielow, University of Stuttgart, D	
<b>205</b>	<b>Precise Voltage Measurement for Power Electronics with High Switching Frequencies</b> .....	<b>1356</b>
	Maximilian Nitzsche, Matthias Zehelein, Nathan Tröster, Jörg Roth-Stielow, University of Stuttgart, D	
<b>206</b>	<b>Fault Diagnosis in Frequency Inverter with Space Vector Recognition of Output Voltage</b> .....	<b>1362</b>
	Rudolf Mecke, Harz University of Applied Sciences, D	
<b>207</b>	<b>Characterization Platform for Modular Power Converters</b> .....	<b>1370</b>
	André Andreta, Yves Lembeye, Jean-Christophe Crébier, Alexis Derbey, University Grenoble Alpes – G2Elab, F; Luiz Fernando Lavado Villa, Univ. Paul Sabatier, LAAS-CNRS, F	
<b>208</b>	<b>Rare-Earth Free EV and HEV Motor Drives: State of the Art</b> .....	<b>1376</b>
	David Cabezuelo, Edorta Ibarra, Estefania Planas, Iñigo Kortabarria, Jose Ignacio Garate, University of the Basque Country (UPV/EHU), ES	

## Thermal Management

<b>209</b>	<b>Application of MMC AISiC Thermocompensators in Power Press Pack Diodes and Thyristors</b> .....	<b>1384</b>
	Alexey Grishanin, Valentin Martynenko, Vyacheslav Eliseev, Mikhail Malygin, Anton Samoylov, Alexander Plotnikov, JSC Electroprivyarnitel, RU; Konstantin Nishchev, Mikhail Novopoltsev, Mordovia State University, RU	
<b>210</b>	<b>Reliability of the Power Module Using the Insulated Substrate with Al/C Composite</b> .....	<b>1388</b>
	Kazuhiko Minami, Shoichiro Wakabayashi, Katsumasa Hirose, Ichiro Ota, Showa Denko, J	

<b>211 A Development of Resin Insulating Material for High Reliable Enhanced Power Module .....</b>	<b>1392</b>
Shinji Amanuma, Mitsuo Togawa, Hitachi Chemical, J	
<b>212 Experimental Investigation of Gravity-Driven Two-Phase Cooling for Power Electronics Applications .....</b>	<b>1395</b>
Devin Pellicone, Advanced Cooling Technologies, USA	
<b>213 Integrated Cooling Channels in Direct Bonded Copper Substrate for Silicon Carbide MOSFETs .....</b>	<b>1400</b>
Alexander Stippich, Maximilian L. J. Battefeld, Rik W. De Doncker, RWTH Aachen, D	
<b>214 Thermoelectric Cooling for Bare Dies Power Devices Embedded in PCB Substrates .....</b>	<b>1408</b>
Shuangfeng Zhang, Eric Laboure, University of Paris, F; Denis Labrousse, Stéphane Lefebvre, ENS Cachan – SATIE, F	
<b>215 Generic Lumped Parameter Thermal Model with Optimized Use of Computational Resources .....</b>	<b>1416</b>
Joaquim Pinol Bel, Heinrich Steinhart, University of Applied Sciences Aalen, D	
<b>216 Methodology and More Accurate Electrothermal Model for Fast Simulation of Power HEMTs .....</b>	<b>1423</b>
Aleš Chvála, Juraj Marek, Luboš Černaj, Patrik Příbytný, Alexander Šatka, Daniel Donoval, Slovak Technical University in Bratislava, SK; Steve Stoffels, Niels Posthuma, Stefaan Decoutere, IMEC, BE	
<b>217 A New Transient Thermal Impedance Model for Estimating the Dynamic Junction Temperature of IGBT Modules .....</b>	<b>1431</b>
Xin Ma, Jia Zhao, Yong Yang, Infineon Integrated Circuit (Beijing), CN	

## Packaging Technologies

<b>218 Effect of Lead Frame Structure and Electrical Characteristic Comparison of IPM Module .....</b>	<b>1436</b>
Samuell Shin, Bumseung Jin, Kangyoon Lee, Jinkyu Choi, Thomas Yim, ON Semiconductor, ROK	
<b>219 Development of 140 × 100 Footprint HV IGBT Module .....</b>	<b>1442</b>
Daohui Li, Fang Qi, Matthew Packwood, Xiang Li, Yangang Wang, Dynex Semiconductor, GB; Xiaoping Dai, Haihui Luo, Guoyou Liu, Wei Zhou, CRRC Times Electric, CN	
<b>220 Performance Comparison Between Surface-Mount and Embedded Power Modules .....</b>	<b>1446</b>
Gerald Weis, AT&S Austria Technologie & Systemtechnik, AT	
<b>221 PCB-Embedding of Power Dies Using Pressed Metal Foam .....</b>	<b>1451</b>
Yoann Pascal, Denis Labrousse, Mickaël Petit, Stéphane Lefebvre, François Costa, SATIE, F	
<b>222 Direct Power Board Bonding Technology for 3D Power Module Package .....</b>	<b>1459</b>
Hidetoshi Ishibashi, Hiroshi Yoshida, Daisuke Murata, Shota Morisaki, Hodaka Rokubuichi, Nobuhiro Asaji, Mitsubishi Electric Corporation, J	
<b>223 A Surface-Mountable 1.2 cc Compact Molded Package Suitable for 13 kV SiC MOSFET .....</b>	<b>1464</b>
Hisato Michikoshi, Hidenori Kitai, Kenji Fukuda, National Institute of Advanced Industrial Science and Technology (AIST), J; Makoto Kanbe, Kazuhiko Omote, Rigaku Corporation, J; Akira Tokuchi, Pulsed Power Japan, J	
<b>224 Particle Prevention During Ultrasonic Welding Process .....</b>	<b>1468</b>
David Guillon, Samuel Hartmann, Remi Guillemin, Pauline Morin, Fabian Fischer, Dominik Truessel, Harald Beyer, Munaf Rahimo, ABB Switzerland – Semiconductors, CH	
<b>225 Asymmetrical Flyback Converter in High Density SMPS .....</b>	<b>1475</b>
Alfredo Medina Garcia, Manfred Schlenk, Infineon Technologies, D; Gerald Deboy, Matthias Joachim Kasper, Infineon Technologies, AT	

## Reliability Aspects

- 226 Reliability Testing of SiC JBS Diodes for Harsh Environment Operation .....1480**  
Thomas Barbieri, Adam Barkley, Edgar Ayerbe, Jonathan Young, Donald Gajewski, Wolfspeed, A Cree Company, USA; Zoltán Major, Vincotech, HU; Matthias Tauer, Vincotech, D
- 227 Mechanical Properties and Reliability of Pressureless Sintered Silver Materials for Power Devices .....1485**  
Masafumi Takesue, Tomofumi Watanabe, Keisuke Tanaka, Naoya Nakajima, Bando Chemical Industries, J
- 228 Control of Partial Discharge with High Temperature Insulating Polymer for High Voltage IGBT Module Application .....1489**  
Muhammad Morshed, Ariful Islam, Thomas Roose, Daniel Longney, Yangang Wang, Andy Dai, Daohui Li, Dynex Semiconductor, GB
- 229 Thermal Characteristics Evaluation of Wide Band Gap Power Devices .....1495**  
Shijo Nagao, Katsuaki Suganuma, Tsuyoshi Funaki, Osaka University, J; Kiyoshi Hirao, AIST Chubu, J; Junichi Susaki, Denka, J; Hideki Sato, Japan Fine Ceramic, J
- 230 From Feasibility to SoP in a 6 Steps Process Described on a SiP Dc-Dc Buck Converter Powermodule .....1498**  
Florian Blum, Dragan Dinulovic, Martin Haug, Michael Brooks, Würth Elektronik, D
- 231 H<sup>3</sup>TRB Test on 1.2 kV SiC MOSFETs .....1506**  
Michael Hanf, Christian Zorn, Nando Kaminski, University of Bremen, D; Martin Domeij, Fredrik Allerstam, Benedetto Buono, Jimmy Franchi, ON Semiconductor, SE; Thomas Neyer, ON Semiconductor, D

## Control and Drive Strategies

- 232 Synchronization and Control of Modular AC- and DC-Sided Parallel-Connected Three-Level NPC Inverters .....1512**  
Jochen Staiger, Swen Bosch, Heinrich Steinhart, University of Applied Sciences Aalen, D
- 233 Comparison of Two Model based Temperature Control Systems Implemented on a Three Level T-Type Inverter .....1520**  
Felix Julian Wölfle, Matthias Pitters, Johannes Ruthardt, Johannes Schuster, Martin Stempfle, Jörg Roth-Stielow, University of Stuttgart, D
- 234 Real-Time Development Interface Embedded in a Compact Motion Controller .....1528**  
Josef Reill, Cristina Serrano Gonzales, Volker Senft, Martin Pfau, DLR – German Aerospace Center, D
- 235 Optimized PWM Technique for Overmodulation Region in Vector Controlled High Speed Drives .....1536**  
Peter Stumpf, Sándor Halász, Budapest University of Technology and Economics, HU
- 236 Dynamic Space Vector Modulation Control for Asymmetric Neutral Point Clamped Multi-level Inverter .....1544**  
Syed Inam Ul Murtaza Shah, Euro Engineering, D
- 237 Short Pulse Transmission for SiC Communicating Gate Driver Under High Dv/Dt .....1552**  
Julien Weckbrodt, Stéphane Azzopardi, Safran, F; Nicolas Ginot, Christophe Batard, University of Nantes – IETR, F
- 238 Advanced Functionality of HVIC Technology for Intelligent Power Module .....1558**  
Jinkyu Choi, Wonhi Oh, Kinam Song, Samuel Shin, ON Semiconductor, ROK

- 239 Three-Level-Gate-Driver to Run Power Transistors in the Saturation Region for Junction Temperature Control .....1562**  
Johannes Ruthardt, Manuel Fischer, Felix Julian Wölfle, Nathan Tröster, Jörg Roth-Stielow, University of Stuttgart, D
- 241 Improved Gate-Drive Unit for RC-IGBT to Overcome Load Current Disturbance in Static MOS-Control .....1570**  
Daniel Lexow, Holger Wiencke, Hans-Günter Eckel, University of Rostock, D
- 243 Assessment-Based Flux Trajectory Optimization and Pulse Width Modulation for Flux Oriented Control: A Comparison .....1577**  
Axel Rothstein, Volker Staudt, Ruhr-University of Bochum, D; Carsten Heising, Avastion, D

### AC-DC, DC-DC Converters


- 244 Resonant Inverter Stage in Modular Converter for Electric Vehicle Charging .....1584**  
Dimitar Arnaudov, Stoyan Vuchev, Dimitar Penev, Nikolay Hinov, Technical University of Sofia, BG
- 245 Modeling and Investigation of Converter Modules Simultaneous Operation in Electric Vehicle Charging Systems .....1591**  
Stoyan Vuchev, Dimitar Arnaudov, Dimitar Penev, Nikolay Hinov, Technical University of Sofia, BG
- 246 SiC-Hybrid Three Level T-Type Rectifier .....1597**  
Florian Störmer, Hans-Günter Eckel, University of Rostock, D
- 247 650 V Silicon Carbide MOSFETs in Totem-Pole Bridgeless PFC Design Achieves High Efficiency (80+ Titanium) Without Adding Complexity and Cost .....1603**  
Adil Salman, Edgar Ayerbe, James Solovey, Guy Moxey, Sei-Hyung Ryu, Adam Barkley, Wolfspeed, USA
- 248 GaN Power ICs and Off-the-Shelf Controllers Enable 150 W, 500 kHz AC-DC with 4x Power Density .....1611**  
Tom Ribarich, Stephen Oliver, Xiucheng Huang, Navitas Semiconductor, USA
- 249 Active Phase Shifting Technique for Inductive Power Transfer (IPT) Systems .....1615**  
Malvika Kamat, Michael Patt, Technology Network Allgäu, D
- 250 Analysis of a ZVS Synchronous Sepic/Zeta DC/DC Converter .....1623**  
Burkhard Ulrich, Baden-Wuerttemberg Cooperative State University Stuttgart, D
- 251 High Efficiency Shoot-Through Modulation Technique for Quasi-Z-Source DC/DC Converters .....1631**  
Yuba Raj Kafle, Graham E. Town, Macquarie University, AU

### DC-AC Converters




- 252 Reducing the dv/dt of Motor Inverters by a Two Leg Resonant Switching Cell .....1636**  
Thomas Fuchslueger, Hans Ertl, Technical University of Vienna, AT;  
Markus Vogelsberger, Bombardier Transportation, AT

- 253 SiC 2.5 MHz Switching Mode Resonant Halfbridge Inverter .....1644**  
Christoph Simon, Fabian Denk, Santiago Eizaguirre, Michael Heidinger, Rainer Kling, Wolfgang Heering, Karlsruhe Institute of Technology (KIT), D

<b>254 Analysis and Design of a Multilayer DC Bus With Low Stray Impedance and Homogenous Current Distribution .....</b>	<b>1652</b>
Asier Matallana, Jon Andreu, Jose Ignacio Garate, Iker Aretxabaleta, Iñigo Kortabarria, University of the Basque Country (UPV/EHU), ES	
<b>255 Replacing Si-IGBTs with SiC-MOSFETs in Low Voltage Grid Converters .....</b>	<b>1660</b>
Marius Kaufmann-Bühler, Hendrik Just, Michael Paluch, Sibylle Dieckerhoff, Technical University of Berlin, D	
<b>256 A Polymer Optical Fiber Bus for Power Electronic Applications .....</b>	<b>1668</b>
Marek Galek, Siemens, D; Jacob Ranftl, Munich University of Applied Sciences, D	
<b>257 High-Inductive Zero-Voltage Commutations within Active-Neutral Point-Clamped Inverters .....</b>	<b>1675</b>
Felix Kayser, Jan Fuhrmann, David Hammes, Hans-Günter Eckel, University of Rostock, D	
<b>258 A SiC-based 15-Level Power Inverter for the Generation of Variable High Frequency Output Voltages .....</b>	<b>1683</b>
Sebastian Fahlbusch, Michael Meissner, Sebastian Klötzer, Felix Bröcker, Klaus F. Hoffmann, Helmut Schmidt University of the Federal Armed Forces Hamburg, D	
<b>259 Loss Optimization for 48 Volt High Current Inverter .....</b>	<b>1691</b>
Matthias Ippisch, Dieter Gerling, University of the Federal Defense Munich, D	
	
<b>260 Common- and Differential-Mode Separators Including the FM Broadcasting Band .....</b>	<b>1699</b>
Karl Oberdieck, Jérôme Gossmann, Andreas Bubert, Rik W. De Doncker, RWTH Aachen, D	
<b>261 Accurate Self-Identification of Inverter Nonlinear Effects in AC Drives .....</b>	<b>1707</b>
Simon Wiedemann, Ralph M. Kennel, Technical University of Munich, D	

### Special Converters

<b>262 Strategy for Reducing Oscillations in Power Electronic Circuits Using Gate Control .....</b>	<b>1714</b>
Lars Middelstaedt, Andreas Lindemann, Otto von Guericke University, D	
<b>263 The newest ST's Super-Junction Power MOSFET Technology for the Best Efficiency in Air Conditioning System .....</b>	<b>1721</b>
Carmelo Parisi, Carmelo Mistretta, STMicroelectronics, I	
	
<b>264 High Efficiency Three-Level Simplified Neutral Point Clamped (3L-SNPC) Inverter with GaN-Si Hybrid Structure .....</b>	<b>1726</b>
Alexander Lange, Jennifer Lautner, Bernhard Piepenbreier, Friedrich Alexander University Erlangen, D	
<b>265 Reducing Astable Relay Power Consumption by the Use of a Constant-Current Buck Converter .....</b>	<b>1733</b>
Michael Heindinger, Christoph Simon, Fabian Denk, Rainer Kling, Wolfgang Heering, Karlsruhe Institute of Technology (KIT), D	
<b>266 Effect of Spurious Resonant Modes on the Operation of Radial Mode Piezoelectric Transformers .....</b>	<b>1740</b>
Jack Forrester, Jonathan Davidson, Martin Foster, University of Sheffield, GB	
<b>267 Fuzzy Logic Based Adaptive Controller for AC/DC Boost Converters .....</b>	<b>1748</b>
Andrea Morici, Infineon Technologies, D; Zain Bin Tariq, Technical University of Munich, D	



- 268 Power Supply System with Integrated Energy Storage for Superconducting Magnets .....1755**  
Maria Papamichali, Emilien Coulinge, Francisco Freijedo, Drazen Dujic, EPFL – Ecole Polytechnique Fédérale de Lausanne, CH



- 269 Novel Thyristor-Based Pulsed Current Converter for a Medical Application – a Conceptual Introduction .....1761**  
Stefan Wettengel, Lars Lindenmüller, Steffen Bernet, Technical University of Dresden, D; Ulrich Schramm, Florian Kroll, Florian-Emanuel Brack, Helmholtz-Zentrum Dresden-Rossendorf, D; Jörg Pawelke, OncoRay – National Center for Radiation Research in Oncology, D

## Power Electronics in Automotive

- 270 Robust Automotive 40 V Power Mosfets for Safer Vehicles .....1767**  
Filippo Scrimizzi, Giuseppe Longo, Giusy Gambino, STMicroelectronics, I
- 271 Large Capacity Power Module Packaging Technology For Automotive Inverter Applications ...1771**  
Yuki Hata, Shoji Saito, Seiichiro Inokuchi, Shinji Hatae, Mitsubishi Electric, J
- 272 Analysis of a Multiphase Multi-Star PMSM Drive System with SiC-Based Inverter for an Automotive Application .....1776**  
Stefan Piepenbreier, Fabian Streit, Maximilian Hofmann, Fraunhofer Institute IISB, D; Julian Berlincke, Robert Plikat, Volkswagen, D; Nicola Burani, Roland Bittner, Semikron Elektronik, D; Serhij Matichyn, EPCOS, D
- 273 Supercapacitors-Based Engine Start Battery Support Device with Active Control .....1786**  
Kaspars Kroics, Riga Technical University, LV
- 274 A Modular DC/DC Converter to Couple a Double Layer Capacitor to the Automotive High Voltage Grid for Short Time Energy Storage .....1792**  
Bastian Strauß, Andreas Lindemann, Otto-von-Guericke-University, D
- 275 Design Optimization of a Three-Phase Bidirectional Dual Active Bridge DC/DC Converter for E-Vehicles Applications .....1800**  
Felipe Bandeira da Silva, Tobias Rafael Fernandes Neto, Federal University of Ceará, BR; Eduardo Façanha de Oliveira, Peter Zacharias, University of Kassel, D
- 276 On-Chip Current Sense: A New Approach for Over Current and Short Circuit Detection for Automotive Main Inverter .....1808**  
Rony Karim, Infineon Technologies, D
- 277 Evaluation of Infineon HybridPACK™ Drive with Optimized Integrated Capacitor/Bus DC Link for High Performance Inverter Applications .....1812**  
Michael Brubaker, Terry Hosking, SBE, USA; Michael Mazzola, Somasundaram Essakiappan, Ehab Shoubaki, Madhav Manjrekar, Energy Production and Infrastructure Center, USA; Tomas Reiter, Infineon Technologies, D
- 278 Multiple Comb Pattern Based Living Object Detection with Enhanced Resolution Design for Wireless Electric Vehicle Chargers .....1818**  
Van X.Thai, Jun H. Park, Seog Y. Jeong, Chun T. Rim, Gwangju Institute of Science and Technology, ROK
- 279 Power Modules for Electric Vehicles SRM Converter .....1824**  
David Cabezuelo, Jon Andreu, Iñigo Kortabarria, Edorta Ibarra, Iñigo Martinez de Alegria, University of the Basque Country (UPV/EHU), ES

## Power Quality, Power Transmission

<b>280 Active Damping for Power Quality Improvement in Grid-Connected Current-Controlled Voltage Source Converters .....</b>	<b>1831</b>
Lorenzo Giuntini, Andrea Mannuccini, GE Consumer & Industrial, CH	
<b>281 Harmonic Current Control in DG-Connected Network Using Proposed Pulse Adaptive VSI ....</b>	<b>1838</b>
Navid Daniali, Euro Engineering, D	
<b>282 Dynamic Performance Evaluation of a dual UPQC Operating Under Power Quality Disturbances .....</b>	<b>1846</b>
Sérgio Augusto Oliveira da Silva, Leonardo Bruno Garcia Campanhol, Vinicius de Souza, Federal University of Technology Parana, BR	
<b>283 Active Filtering of DC Ripple Currents Between Converter and Low-Resistive DC Load .....</b>	<b>1854</b>
Sebastian Raab, Ansgar Ackva, University of Applied Sciences Würzburg-Schweinfurt, D	
<b>284 Dynamic Control and Design of a Modular Power Flow Controller for HVDC Networks with Fault Clearing Capabilities .....</b>	<b>1860</b>
Daniel Dinkel, Claus Hillermeier, Rainer Marquardt, University of the Federal Armed Forces Munich, D	
<b>285 Multi-Terminal HVDC Grid Control Using a Fictitious, Model Based Machine Set .....</b>	<b>1868</b>
Steffen Menzel, Alexander Ernst, Johannes Adler, Bernd Orlik, University of Bremen, D	
<b>286 Research on Solid State Circuit Breaker Based on SiC MOSFET with Soft Switch off Method .....</b>	<b>1876</b>
Haihong Qin, Ying Zhang, Yaowen Dong, Kefeng Xu, Shishan Wang, Nanjing University of Aeronautics and Astronautics, CN; Chaohui Zhao, Shanghai DianJi University	

## Software Tools and Applications

<b>288 Predicting ZVS Behavior of Resonant Converters Using a Fast and Effective Calculation Method .....</b>	<b>1882</b>
Christian Oeder, Markus Barwig, Thomas Dürbaum, Friedrich Alexander University of Erlangen, D	
<b>289 A Novel Combination of Algorithms for Accelerated Convergence to Steady-State .....</b>	<b>1889</b>
Benedikt Kohlhepp, Jens Göttle, Eva Schmidt, Thomas Dürbaum, Friedrich Alexander University of Erlangen-Nuremberg, D	
<b>290 A Novel Detailed Analysis of the Boost Converter Utilizing Nonlinear Inductance and Capacitance .....</b>	<b>1896</b>
Panagiotis Mantzanas, Erdi Bayrakdar, Daniel Kübrich, Thomas Dürbaum, Friedrich Alexander University of Erlangen, D	
<b>291 Performance Analysis of IGCT Clamp Circuit and Thermal Loss Modeling of IGCT Based Converters for High Power Applications .....</b>	<b>1904</b>
Madhan Mohan, Anup Kavimandan, ABB Global Industries and Services, IN; Umamaheswara Vemulapati, Evgeny Tsyplakov, Munaf Rahimo, ABB Switzerland, CH	
<b>292 SMPS Protection Against Lightning Effects .....</b>	<b>1911</b>
Claudio Mazzurco, STMicroelectronics, I	
<b>293 Power Loss Breakdown in BLDC Drives Applications Using MATLAB .....</b>	<b>1919</b>
Hrach Amirkhani, Infineon Technologies, USA; Steve Oknaian, Infineon Technologies Americas, USA	

- 294 Statistical Modelling Method for Active Power Components Based on Datasheet Information .....1924**  
 André Andreta, Yves Lembeye, Jean-Christophe Crébier, University Grenoble Alpes – G2Elab, F;  
 Luiz Lavado Villa, LAAS – CNRS, F
- 295 Fast Solver to Get Steady-State Waveforms for Power Converter Design .....1931**  
 Guillaume Fontes, Regis Ruelland, Alvaro Morentin, Guillaume Delamare, Nicolas Videau,  
 Adel Ziani, Power Design Technologies, F; Thierry Meynard, University de Toulouse, F
- 296 System Complexity Reduction Approach in the Modelling of a Discrete Power Device .....1938**  
 Daniela Cavallaro, Alessandra Cascio, Giuseppe Greco, STMicroelectronics, I
- 297 Automated Medium Voltage Virtual Test Bench Using Hardware-in-the-Loop .....1943**  
 Emmanuel Frappé, Alain Dutrey, François Malrait, Schneider Electric, F

### Keynotes

- 298 Electric Vehicles Charging – An Ultrafast Overview .....N/A**  
 Drazen Dujic, Power Electronics Laboratory, EPFL, CH
- 299 New Passive Devices in Power Conversion – Nice to Have or a Must? .....N/A**  
 Petar J. Grbovic, Huawei Technologies, D
- 300 Modular Multilevel Submodules for Converters, from the State of the Art to Future Trends .....N/A**  
 Markus Billmann, Fraunhofer Institute IISB, D